

METHOD FOR RECONSTRUCTING AN INTEGRATED CIRCUIT PACKAGE USING LAPPING

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ABSTRACT

A method is provided for reconstructing an integrated circuit package

5 comprising: attaching a die to exposed wire bond pads of a lead frame so that the die is electrically connected to the lead frame; and encapsulating the die and the wire bond pads in an encapsulant; and reshaping an upper surface of the encapsulant where at least a portion of the encapsulant reshaping is performed by a lapping process.

LAPPING INTEGRATED CIRCUIT PACKAGE